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Electronic Patent Application Submission

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Application ID: 10605041



Title of Invention: METAL INJECTION MOLDING
MATERIAL WITH HIGH ASPECT
RATIO FILLER

First Named Inventor: Kevin McCULLOUGH

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-03

Effective Receipt Date: 2004-01-06

Submission Type: Information Disclosure
Statement

Filing Type:

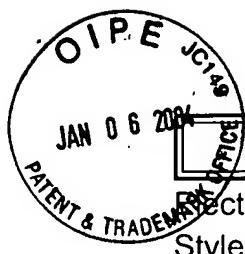
Confirmation number: 2040

Attorney Docket Number: C001P00404US2

Total Fees Authorized:

Digital Certificate Holder: cn=David Josephs,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US

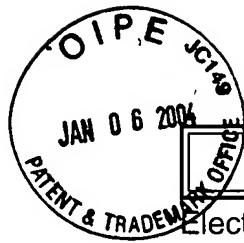
Certificate Message Digest: 46f55b79c1a4798dd0deb30a51c486286efd9b9e



TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	METAL INJECTION MOLDING MATERIAL WITH HIGH ASPECT RATIO FILLER	
Application Number:	10/605041	
Date:	2003-09-03	
First Named Applicant:	Mr. Kevin A. McCULLOUGH	
Confirmation Number:	2040	
Attorney Docket Number:	C001P00404US2	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mr. David R. Josephs Registered Number: 34,632	/david r. josephs/	Attorney
Documents being submitted us-ids	Files P0404US2-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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Application Number:	10/605041 						
Confirmation Number:	2040						
First Named Applicant:	Kevin McCULLOUGH						
Attorney Docket Number:	C001P00404US2						
Art Unit:	1775						
Search string:	(T904012 or 3398233 or 3673121 or 3708387 or 40998945 or 4307147 or 4367745 or 4496475 or 4568592 or 4664971 or 4689250 or 4689250 or 4816184 or 5011870 or 5011872 or 5011870 or 5021494 or 5098610 or 5106540 or 5180513 or 5213715 or 5213715 or 5225110 or 5286416 or 5302456 or 5334330 or 5373046 or 5397608 or 5445308 or 5490319 or 5522962 or 5536568 or 5580493 or 56693811 or 5681883 or 5770305 or 5834337 or 5851644 or 5863467 or 5945217 or 6048919 or 4470063 or 5037590 or 5373046 or 5400505 or 5454425 or 5552214 or 5660923 or 5981085 or 6139783 or 6303096 or 20020022686 or 20020025998).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	3398233	1968-08-20	Lizasoain et al.	174	110	
	3	3673121	1972-06-27	Meyer	252	511	
	4	3708387	1973-01-02	Turner et al.	161	168	
	5	40998945	1978-07-04	Oehmke	428	327	
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	7	4367745	1983-01-11	Welage	128	303.13	
	8	4496475	1985-01-29	Abrams	252	514	
	9	4568592	1986-02-04	Kawaguchi et al.	428	107	

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428	288
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428	328
438	122
428	213
252	511
428	389
524	404
357	67
264	29.2
524	413
29	889

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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	2	20020025998	2002-02-28	McCullough et al.	A1	524	66

Signature

Examiner Name	Date